

REMARKS

In the Office Action, the Examiner rejected claims 1-2 and 5-21 under 35 U.S.C. §102(b) as being anticipated by United States Patent No. 5,864,394 (Jordan, III et al.), rejected claim 3 under 35 U.S.C. §103(a) as being unpatentable over Jordan, III et al. in view of United States Patent No. 6,885,950 (Misutake et al.), and rejected claim 4 under 35 U.S.C. 103(a) as being unpatentable over Jordan, III et al. in view of United States Patent No. 7,065,239 (Maaya et al.). Applicant respectfully traverses.

Claim 1 specifically claims, among other things, the step of defining an appropriate product/device input dataset for a plurality of different die sizes and products, wherein the dataset comprises information relating to the size of each die in two directions as well as the location of at least one of the corners of each die. Claim 1 also claims using this dataset to generate a table of lots and wafer of a product/device with a virtual die coordinate for each die and a corresponding value.

In the Office Action, the Examiner asserted that Figure 7 of Jordan, III et al. discloses “information relating to the size of each die in two directions as well as the location of at least one of the corners of each die.” While this may be true, Applicant is not merely claiming that. Applicant is claiming the step of defining an appropriate product/device input dataset for a plurality of different die sizes and products (wherein the dataset comprises physical correlation reference points comprising information relating to the size of each die in two directions as well as the location of at least one of the corners of each die), and collecting a die level yield bin dataset for one of the products/devices by using the product/device input dataset to generate a

table of data for the lots and wafers of said one of the products/devices with a virtual die coordinate for each die and a corresponding value.

Figure 7 of Jordan, III et al. merely illustrates a wafer, and the fact that it includes a repeating pattern (see col. 12, lines 37-43). Figure 7 of Jordan, III et al. discloses a plurality of dies on a wafer and that the dies have corners, etc., but does not disclose providing a dataset which comprises information relating to the size of each die in two directions as well as the location of at least one of the corners of each die.

Applicant respectfully submits that Jordan, III et al. fails to disclose defining a dataset as recited in claim 1 (i.e., one which comprises physical correlation reference points comprising information relating to the size of each die in two directions as well as the location of at least one of the corners of each die), let alone using the dataset as recited in claim 1 (i.e., to generate a table of data for the lots and wafers of said one of the products/devices with a virtual die coordinate for each die and a corresponding value).

Additionally, Applicant respectfully submits that Jordan, III et al. is very different from the present invention. Jordan, III et al. deals with scanning for anomalies. That is not what the present invention is directed to. In contrast, the present invention is directed to calculating high-resolution wafer parameter profiles.

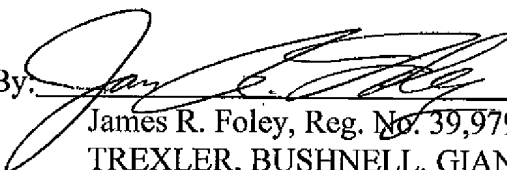
Figure 7 of Jordan, III et al. merely illustrates a wafer, and the fact that it includes a plurality of dies on a wafer and that the dies have corners, etc. However, no where is it disclosed or suggested to provide a dataset which comprises information relating to the size of each die in two directions as well as the location of at least one of the corners of each die, and using this

dataset to generate a table of data for the lots and wafers of said one of the products/devices with a virtual die coordinate for each die and a corresponding value.

Applicant respectfully submits that the claims of the application are allowable over the rejections of the Examiner. Should the present claims not be deemed adequate to effectively define the patentable subject matter, the Examiner is respectfully urged to call the undersigned attorney of record to discuss the claims in an effort to reach an agreement toward allowance of the present application.

Respectfully submitted,

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